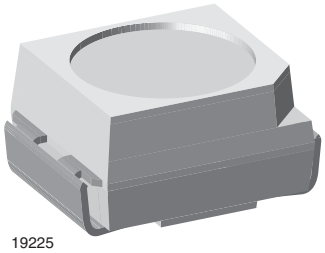
Low Current SMD LED PLCC-2



19225

FEATURES

- SMD LED with exceptional brightness
- Compatible with automatic placement equipment
- EIA and ICE standard package
- Compatible with infrared, vapor phase and wave solder processes according to CECC
- Available in 8 mm tape
- Low profile package
- Non-diffused lens: excellent for coupling to light pipes and backlighting
- Very low power consumption
- Luminous intensity ratio in one packaging unit $I_{Vmax.}/I_{Vmin.} \leq 1.6$
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE GREEN (5-2008)

DESCRIPTION

These new devices have been designed to meet the increasing demand for low current SMD LEDs.

The package of the VLMT3100 is the PLCC-2 (equivalent to a size B tantalum capacitor).

It consists of a lead frame which is embedded in a white thermoplast. The reflector inside this package is filled up with clear epoxy.

PRODUCT GROUP AND PACKAGE DATA

- Product group: LED
- Package: SMD PLCC-2
- Product series: Low current
- Angle of half intensity: ± 60°

APPLICATIONS

- Automotive: backlighting in dashboards and switches
- Telecommunication: indicator and backlighting in telephone and fax
- Indicator and backlight for audio and video equipment
- Indicator and backlight for battery driven equipment
- Small indicator for outdoor applications
- Indicator and backlight in office equipment
- Flat backlight for LCDs, switches, and symbols
- General use

PARTS TABLE

PART	COLOR	LUMINOUS INTENSITY (mcd)			at I_F (mA)	WAVELENGTH (nm)			at I_F (mA)	FORWARD VOLTAGE (V)			at I_F (mA)	TECHNOLOGY
		MIN.	TYP.	MAX.		MIN.	TYP.	MAX.		MIN.	TYP.	MAX.		
VLMT3100-GS08	Red	0.28	1.1	-	2	612	618	625	2	-	2.2	2.9	2	GaAsP on GaP
VLMT3100-GS18	Red	0.28	1.1	-	2	612	618	625	2	-	2.2	2.9	2	GaAsP on GaP

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)

VLMT3100

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage (1)		V_R	6	V
DC forward current		I_F	7	mA
Surge forward current	$t_p \leq 10$ µs	I_{FSM}	0.5	A
Power dissipation		P_V	20	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +100	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	t ≤ 5 s	T_{sd}	260	°C
Thermal resistance junction / ambient	Mounted on PC board (pad size > 16 mm²)	R_{thJA}	500	K/W

Note

(1) Driving the LED in reverse direction is suitable for short term application

OPTICAL AND ELECTRICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified) VLMT3100, RED						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Luminous intensity (1)	I_F = 2 mA	I_V	0.28	1.1	-	mcd
Dominant wavelength	I_F = 2 mA	λ_d	612	618	625	nm
Peak wavelength	I_F = 2 mA	λ_p	-	635	-	nm
Angle of half intensity	I_F = 2 mA	φ	-	± 60	-	deg
Forward voltage	I_F = 2 mA	V_F	-	2.2	2.9	V
Reverse voltage	I_R = 10 µA	V_R	6	15	-	V
Junction capacitance	V_R = 0 V, f = 1 MHz	C_j	-	50	-	pF

Note

(1) In one packing unit $I_{Vmax.}/I_{Vmin.} \leq 1.6$

LUMINOUS INTENSITY CLASSIFICATION		
GROUP	**LUMINOUS INTENSITY (mcd)**	
	MIN.	**MAX.**
C1	0.28	0.36
C2	0.36	0.45
D1	0.45	0.56
D2	0.56	0.71
E1	0.71	0.90
E2	0.9	1.12
F1	1.12	1.4
F2	1.4	1.8
G1	1.8	2.24
G2	2.24	2.8

Note

- Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of ± 11 %.
  The above type numbers represent the order groups which include only a few brightness groups. Only one group will be shipped on each reel (there will be no mixing of two groups on each reel). In order to ensure availability, single brightness groups will not be orderable.
  In a similar manner for colors where wavelength groups are measured and binned, single wavelength groups will be shipped on any one reel.
  In order to ensure availability, singe wavelength groups will not be orderable.

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

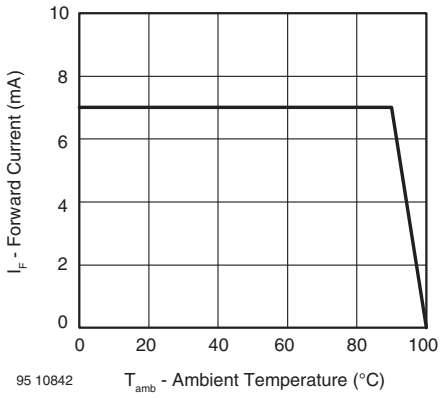


Fig. 1 - Forward Current vs. Ambient Temperature

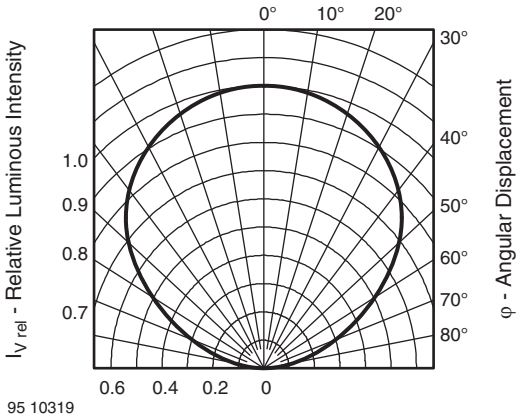


Fig. 2 - Relative Luminous Intensity vs. Angular Displacement

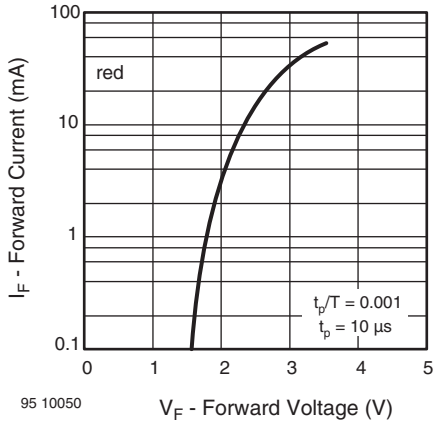


Fig. 3 - Forward Current vs. Forward Voltage

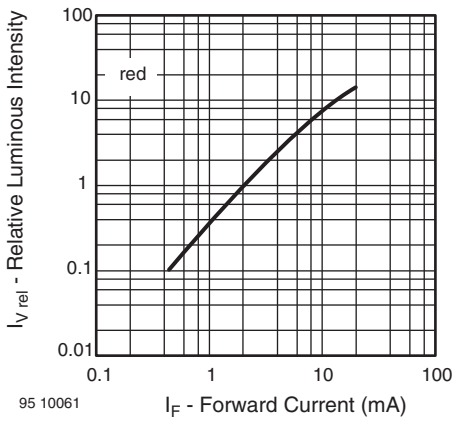


Fig. 6 - Relative Luminous Intensity vs. Forward Current

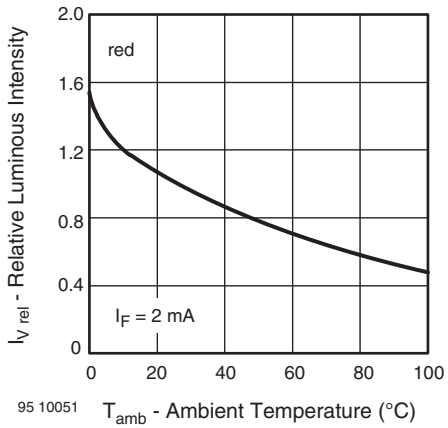


Fig. 4 - Relative Luminous Intensity vs. Ambient Temperature

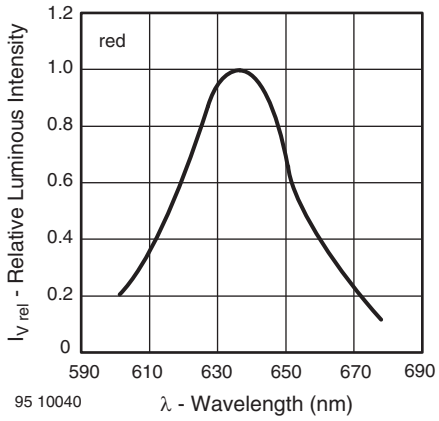


Fig. 7 - Relative Intensity vs. Wavelength

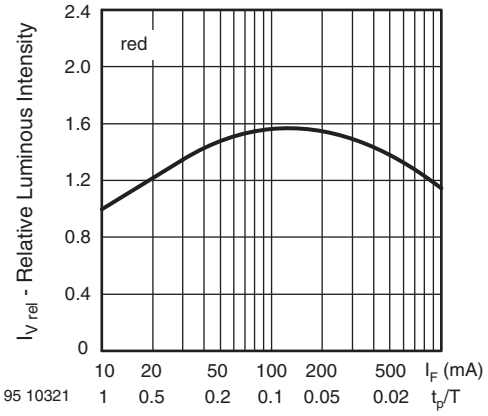
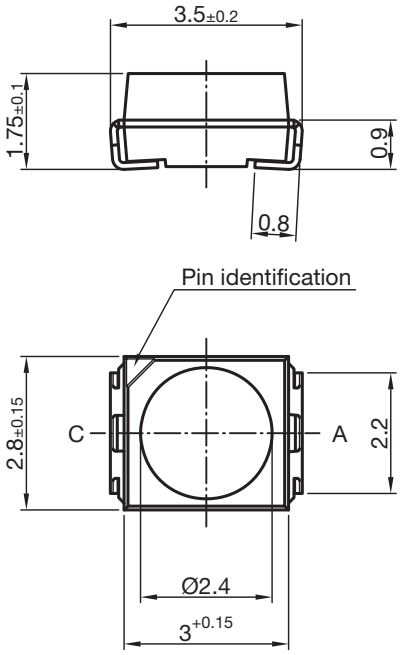


Fig. 5 - Relative Luminous Intensity vs. Forward Current/Duty Cycle

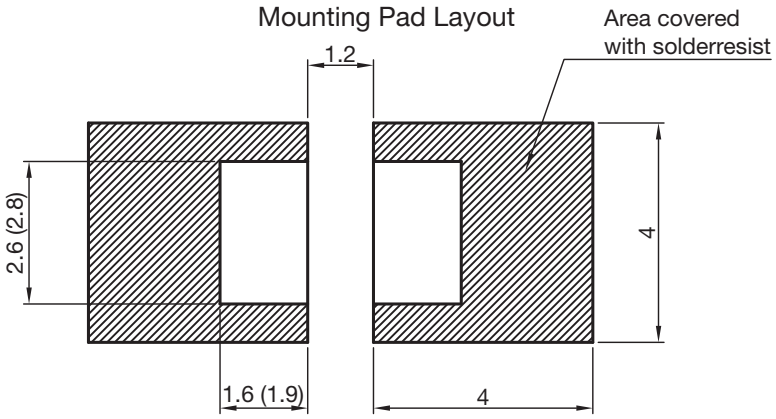
PACKAGE DIMENSIONS in millimeters



Technical drawings according to DIN specifications

Dimensions in mm

Drawing-No.: 6.541-5067.01-4
Issue: 6; 23.09.13

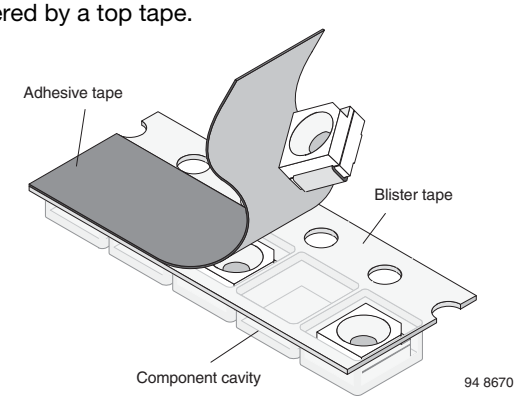


Dimensions: Reflow and vapor phase (wave soldering)

METHOD OF TAPING / POLARITY AND TAPE AND REEL

SMD LED (VLM.3-SERIES)

Vishay's LEDs in SMD packages are available in an antistatic 8 mm blister tape (in accordance with DIN IEC 40 (CO) 564) for automatic component insertion. The blister tape is a plastic strip with impressed component cavities, covered by a top tape.



TAPING OF VLM.3...

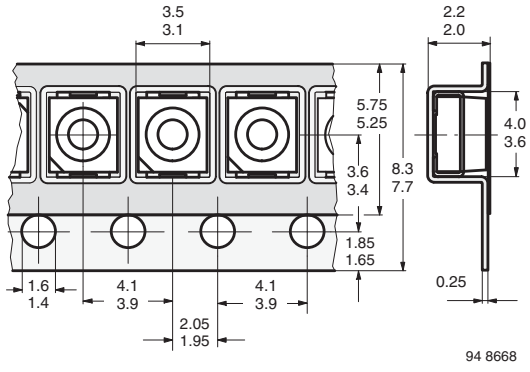


Fig. 8 - Tape Dimensions in mm for PLCC-2

REEL PACKAGE DIMENSION IN MILLIMETERS FOR SMD LEDS, TAPE OPTION GS08 (= 1500 PCS.)

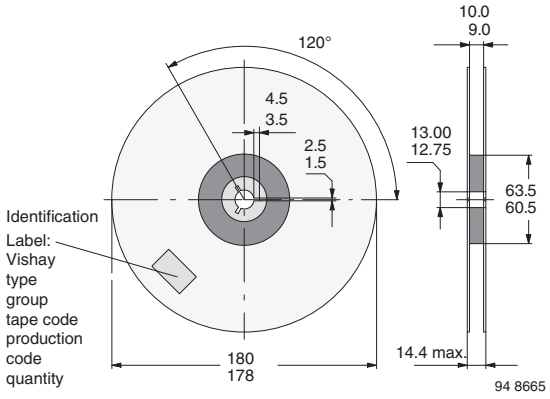


Fig. 9 - Reel Dimensions - GS08

REEL PACKAGE DIMENSION IN MILLIMETERS FOR SMD LEDS, TAPE OPTION GS18 (= 8000 PCS.) PREFERRED

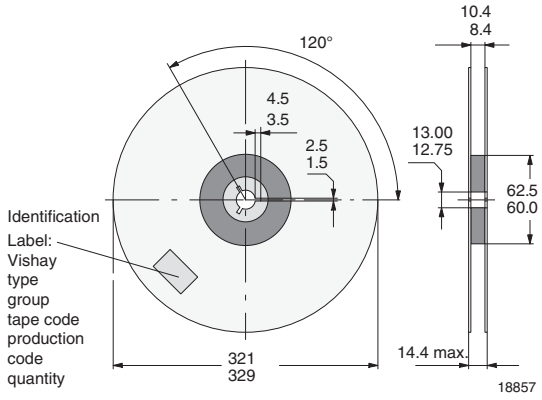


Fig. 10 - Reel Dimensions - GS18

SOLDERING PROFILE

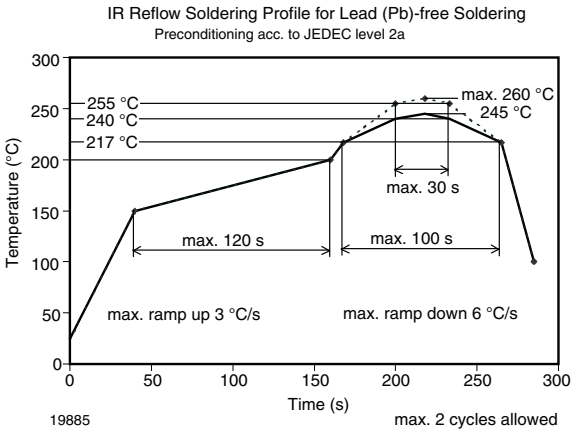


Fig. 11 - Vishay Lead (Pb)-free Reflow Soldering Profile (acc. to J-STD-020)

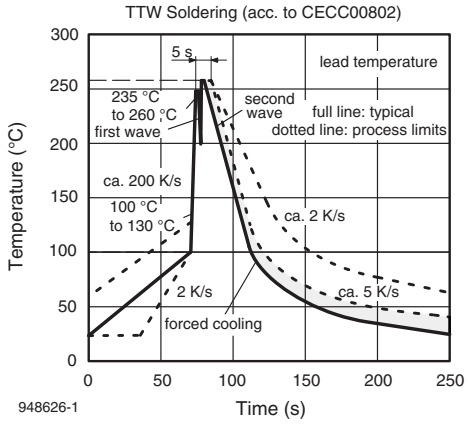
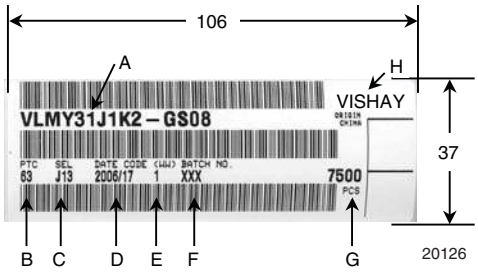


Fig. 12 - Double Wave Soldering of Opto Devices (all Packages)

BAR CODE PRODUCT LABEL (example)



A. Type of componenent

B. Manufacturing plant

C. SEL - selection code (bin):
e.g.: J1 = code for luminous intensity group
3 = code for color group

D. Date code year / week

E. Day code (e.g. 1: Monday)

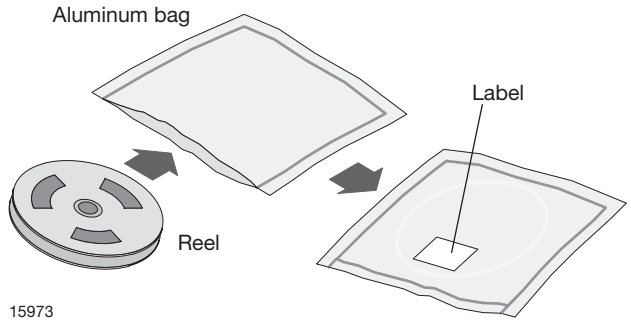
F. Batch no.

G. Total quantity

H. Company code

DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

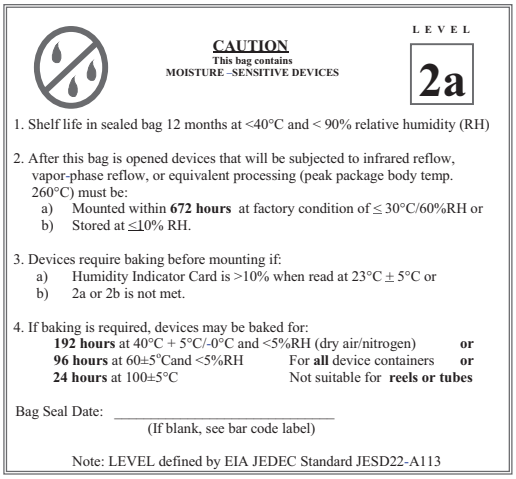
- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 672 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or
96 h at 60 °C + 5 °C and < 5 % RH for all device containers or
24 h at 100 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC® standard JESD22-A112 level 2a label is included on all dry bags.


CAUTION
This bag contains
MOISTURE –SENSITIVE DEVICES

LEVEL
2a

1. Shelf life in sealed bag 12 months at <40°C and < 90% relative humidity (RH)

2. After this bag is opened devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing (peak package body temp. 260°C) must be:
a) Mounted within **672 hours** at factory condition of ≤ 30°C/60%RH or
b) Stored at ≤10% RH.

3. Devices require baking before mounting if:
a) Humidity Indicator Card is >10% when read at 23°C ± 5°C or
b) 2a or 2b is not met.

4. If baking is required, devices may be baked for:
192 hours at 40°C + 5°C/-0°C and <5%RH (dry air/nitrogen) **or**
96 hours at 60±5°Cand <5%RH For **all** device containers **or**
24 hours at 100±5°C Not suitable for **reels or tubes**

Bag Seal Date: _____
(If blank, see bar code label)

Note: LEVEL defined by EIA JEDEC Standard JESD22-A113

19786

Example of JESD22-A112 level 2a label

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABEL

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay’s knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer’s responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer’s technical experts. Product specifications do not expand or otherwise modify Vishay’s terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.